

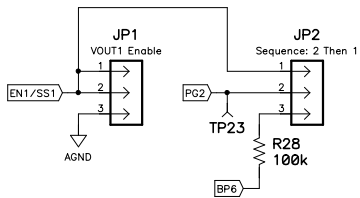
Component Current Stress

- \* L1: 7.9A peak, 7.1A rms
- \* Q1 high-side: 7.9A peak, 4.5A rms
- \* Q1 low-side: 7.9A peak, 5.4A rms
- \* L2: 4.5A peak, 4.1A rms
- \* Q2 high-side: 4.5A peak, 2.1A rms
- \* Q2 low-side: 4.5A peak, 3.4A rms

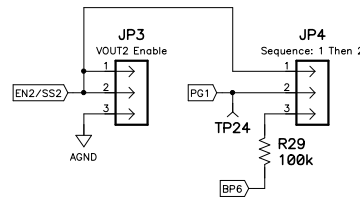
Output 1  
5.0V @ 7.0A

Output 2  
3.3V @ 4.0A

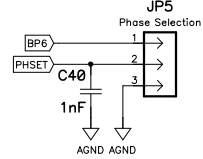
fswitch = 500 kHz



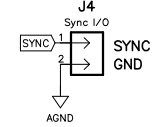
Float: Enabled  
Low: Disabled



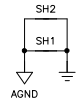
Float: Enabled  
Low: Disabled



High: Slave Mode (90/270 deg)  
Float: Slave Mode (0/180 deg)  
Low: Master Mode (0/180 deg)



Ext. Sync Input/Output



GNDs tied together on internal PCB layers

Notes

- \* R7, R24 for test purpose only
- \* Modified EVM TPS40322EVM-679
- \* Parts with RefDes >100 have no footprint on PCB

\*\* PRELIMINARY \*\*

Title Dual Buck 5.0V @ 7.0A / 3.3V @ 4.0A		
Size C	Number PMP8703	Rev B
Date 10/10/2013	Drawn by M. Ulmann	
Filename PMP8703RevB.sch	Sheet 1	of 1

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